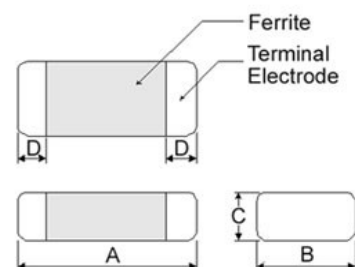




### FEATURES

- Internal silver printed layers and magnetic shielded structures to minimize crosstalk
- Monolithic structure for excellent reliability
- Smaller DC resistance and larger allowable current than CVB series
- Can be used in a wide range of frequency to suppress EMI



### Shape and Dimensions

Unit: mm [inch]

Type	A	B	C	D
1005 [0402]	1.0±0.15 [.039±.006]	0.5±0.15 [.020±.006]	0.5±0.15 [.020±.006]	0.25±0.1 [.010±.004]
1608 [0603]	1.65±0.15 [.065±.006]	0.8±0.15 [.031±.006]	0.5±0.15 [.021±.006]	0.3±0.2 [.012±.008]
1608 [0603]	1.65±0.15 [.065±.006]	0.8±0.15 [.031±.006]	0.8±0.15 [.031±.006]	0.3±0.2 [.012±.008]
2012 [0805]	2.0 ±0.15 [.079 ±0.05]	1.2±0.2 [.049±.008]	0.9±0.2 [.033±.008]	0.5±0.3 [.020±.012]
3216 [1206]	3.2±0.15 [0.13 ±0.05]	1.6±0.2 [.062±.008]	0.9±0.2 [.033±.008]	0.5±0.3 [.020±.012]

### PRODUCT IDENTIFICATION

CVB                      1608                      E                      221                      T  
①                                      ②                                      ③                                      ④                                      ⑤

①

EMI BEADS	
CVB	Chip Ferrite Bead For

②

External Dimensions (L×W) (mm)	
1005 [0402]	1.0×0.5
1608 [0603]	1.65×0.8
2012 [0805]	2.0×1.25
3216 [1206]	3.2×1.65

③

Type	
E	Large Current

④

Nominal Impedance	
Example	Nominal Value
300	30Ω
221	220Ω
102	1000Ω

⑤

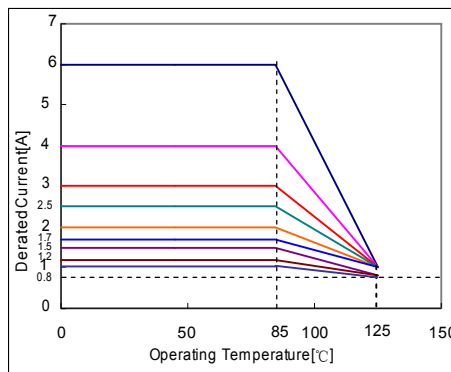
Packing	
T	Tape & Reel



### DETAIL ELECTRICAL CHARACTERISTICS

#### Rated Current

When operating temperatures exceed +85°C, derating of current is necessary for chip ferrite beads for which rated current is 1000mA and over. Please apply the derating curve shown in chart according to the operating temperature.



### CVB1005 E TYPE

Part Number	Impedance	Z Test Frequency	Max. DC Resistance	Max. Rated Current
Units	$\Omega$	MHz	$\Omega$	mA
Symbol	Z	Freq.	DCR	I <sub>r</sub>
CVB1005E100T	10±25%	100	0.03	2000
CVB1005E300T	30±25%	100	0.05	1700
CVB1005E600T	60±25%	100	0.07	1500
CVB1005E800T	80±25%	100	0.09	1200
CVB1005E121T	120±25%	100	0.09	1400
CVB1005E151T	150±25%	100	0.14	1400
CVB1005E221T	220±25%	100	0.18	1100
CVB1005E601T	600±25%	100	0.34	700
CVB1005E102T	1000±25%	100	0.49	500

### CVB1608 E TYPE

Part Number	Impedance	Z Test Frequency	Max. DC Resistance	Max. Rated Current
Units	$\Omega$	MHz	$\Omega$	mA
Symbol	Z	Freq.	DCR	I <sub>r</sub>
CVB1608E100T	10±25%	100	0.02	4000
CVB1608E300T	30±25%	100	0.03	3000
CVB1608E400T	40±25%	100	0.03	3000
CVB1608E600T	60±25%	100	0.04	3000
CVB1608E101T	100±25%	100	0.07	2700
CVB1608E121T	120±25%	100	0.08	2500
CVB1608E151T	150±25%	100	0.08	2000
CVB1608E181T	180±25%	100	0.09	2000
CVB1608E221T	220±25%	100	0.10	2000
CVB1608E301T	300±25%	100	0.12	1500
CVB1608E471T	470±25%	100	0.15	1200
CVB1608E601T	600±25%	100	0.20	1000
CVB1608E102T	1000±25%	100	0.25	800
CVB1608E152T	1500±25%	100	0.40	500


**CVB2012 E TYPE**

Part Number	Impedance	Z Test Frequency	Max. DC Resistance	Max. Rated Current
Units	$\Omega$	MHz	$\Omega$	mA
Symbol	Z	Freq.	DCR	I <sub>r</sub>
CVB2012E100T	10±25%	100	0.01	6000
CVB2012E600T	60±25%	100	0.03	3000
CVB2012E121T	120±25%	100	0.04	3000
CVB2012E221T	220±25%	100	0.08	2000
CVB2012E301T	300±25%	100	0.08	2000
CVB2012E471T	470±25%	100	0.10	2000
CVB2012E601T	600±25%	100	0.10	2000
CVB2012E102T	1000±25%	100	0.12	1500
CVB2012E222T	2200±25%	100	0.60	200

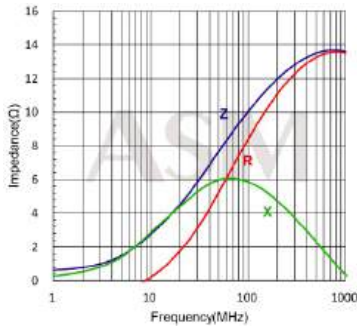
**CVB3216 E TYPE**

Part Number	Impedance	Z Test Frequency	Max. DC	Max. Rated Current
Units	$\Omega$	MHz	$\Omega$	mA
Symbol	Z	Freq.	DCR	I <sub>r</sub>
CVB3216E190T	19±25%	100	0.01	5000
CVB3216E300T	30±25%	100	0.01	4000
CVB3216E600T	60±25%	100	0.02	4000
CVB3216E101T	100±25%	100	0.03	3000
CVB3216E121T	120±25%	100	0.03	3000
CVB3216E221T	220±25%	100	0.05	2000
CVB3216E301T	300±25%	100	0.06	2000
CVB3216E501T	500±25%	100	0.10	2000
CVB3216E601T	600±25%	100	0.10	2000
CVB3216E102T	1000±25%	100	0.15	1200

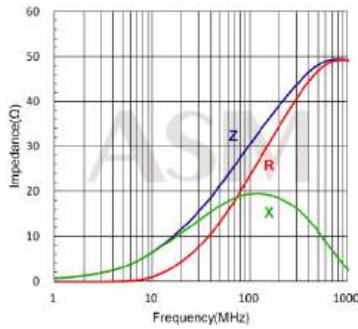


### CVB1005 E TYPE

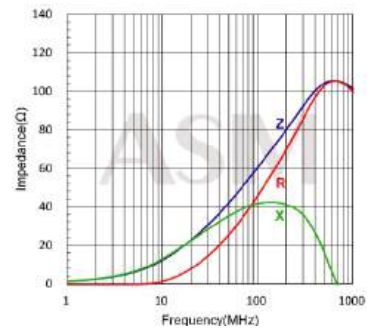
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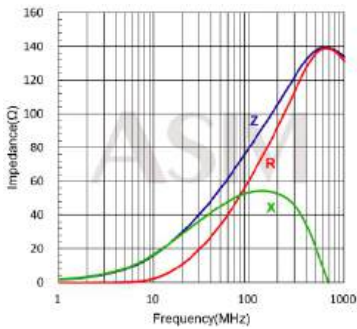
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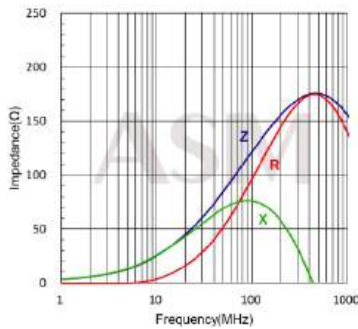
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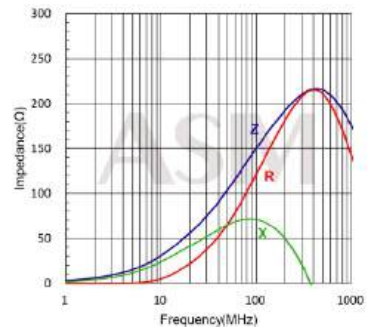
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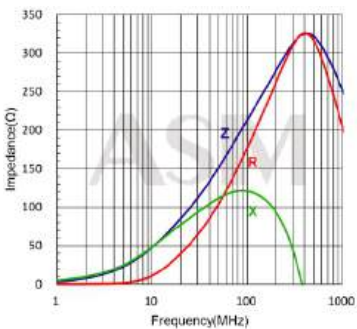
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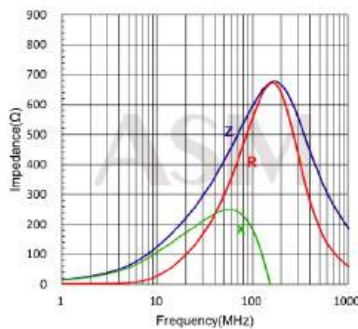
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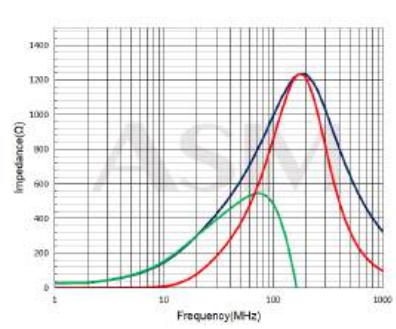
CVB1005E221T



CVB1005E601T

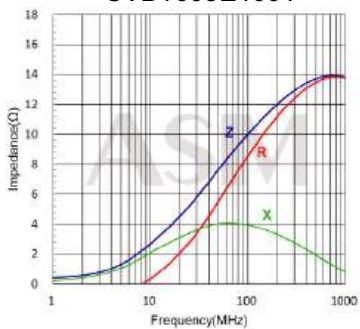


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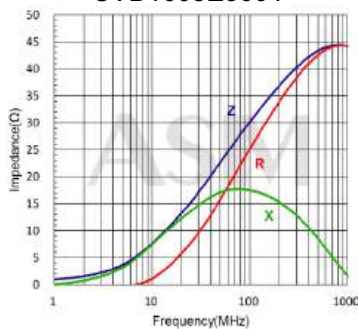


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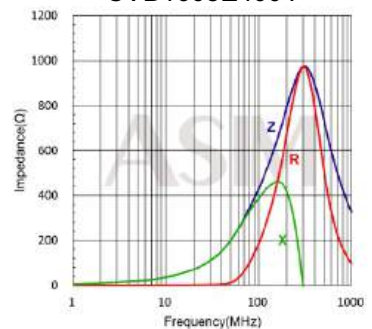
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CVB1608E300T

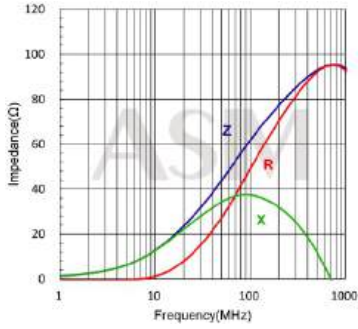


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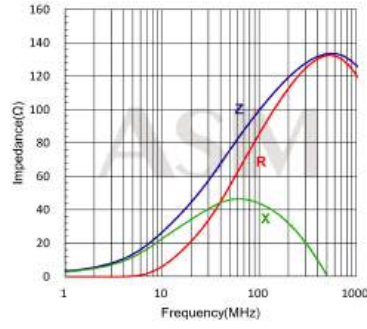




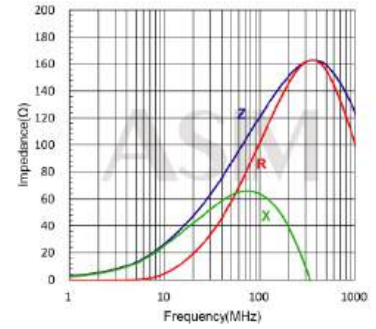
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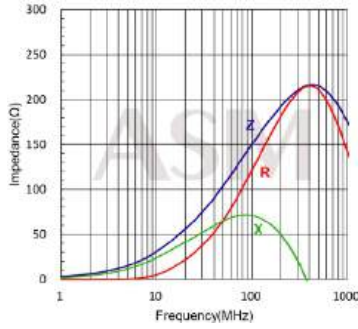
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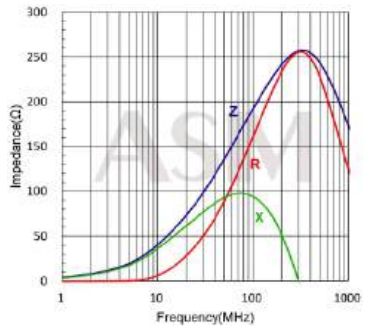
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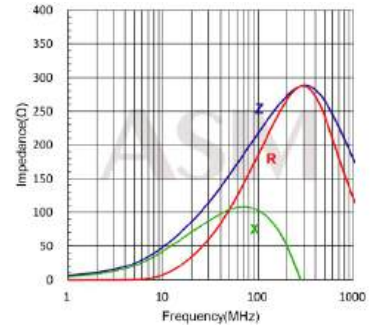
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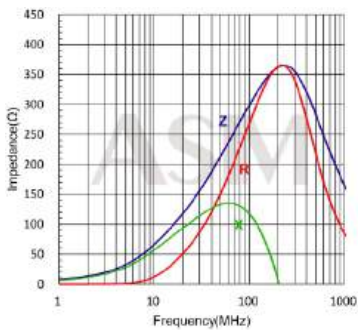
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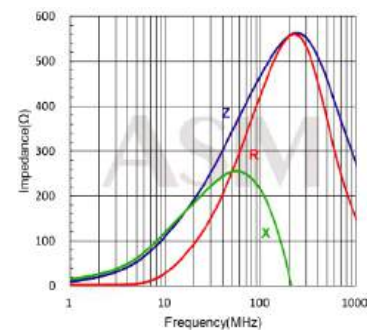
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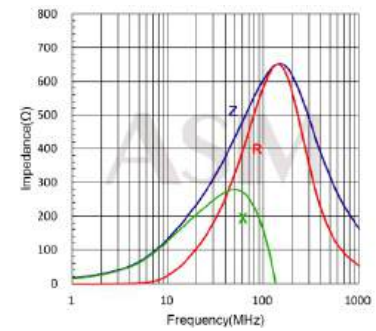
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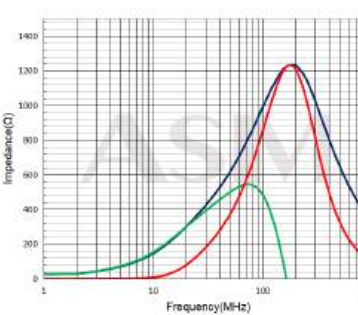
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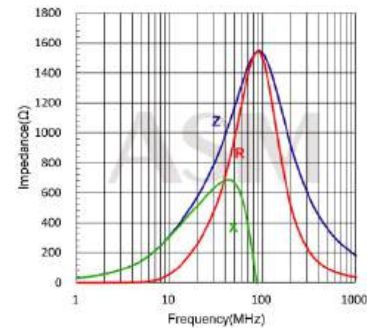
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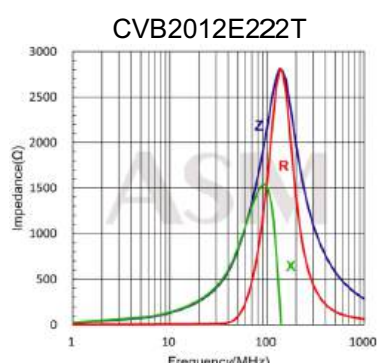
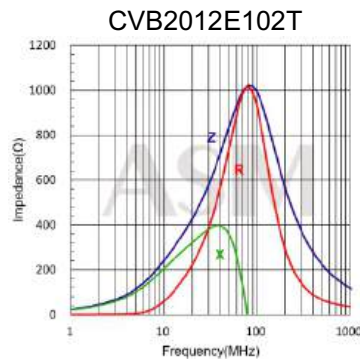
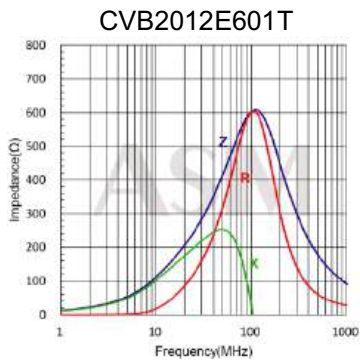
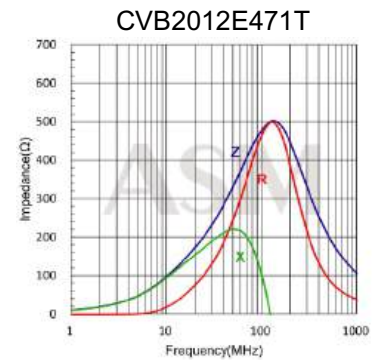
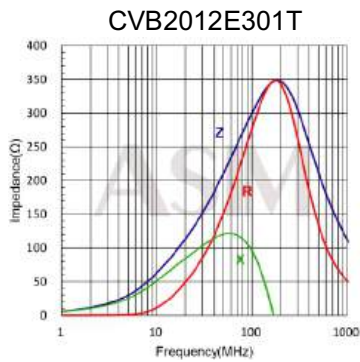
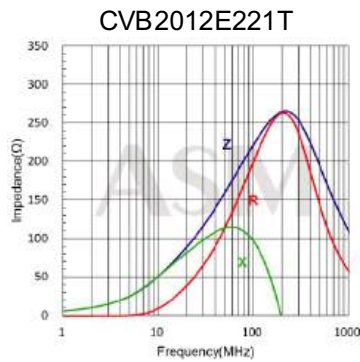
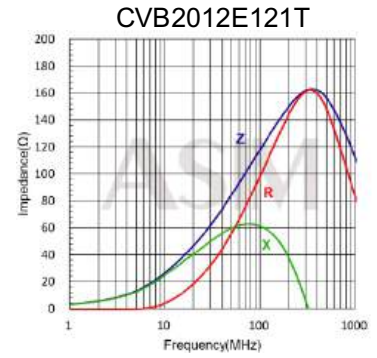
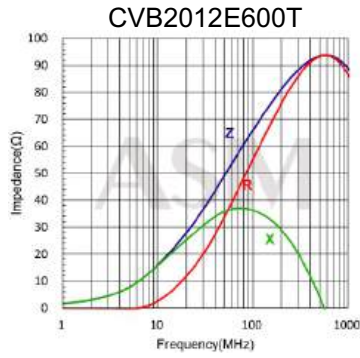
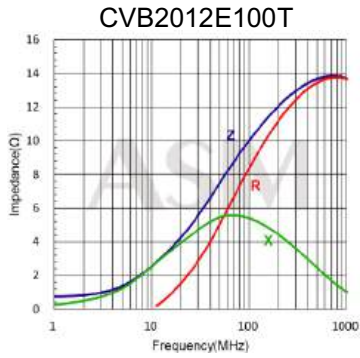


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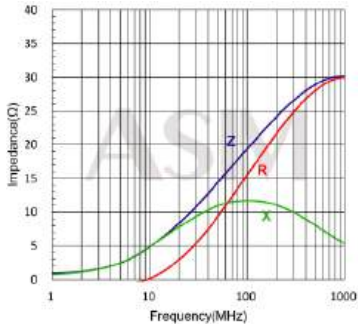
### CVB2012 E TYPE



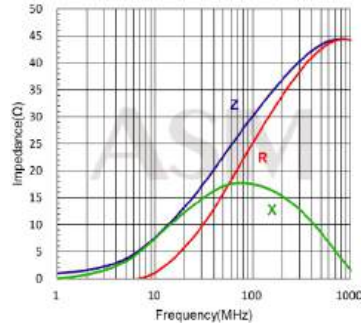


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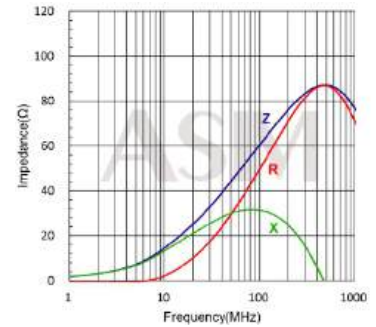
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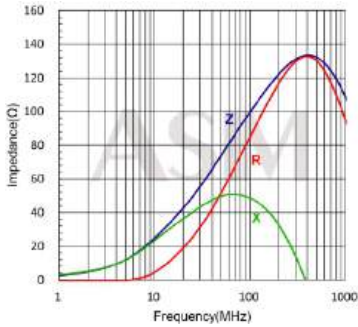
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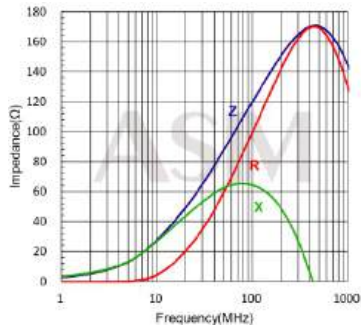
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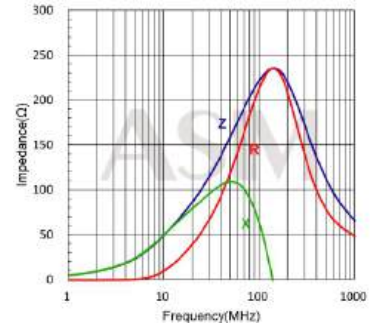
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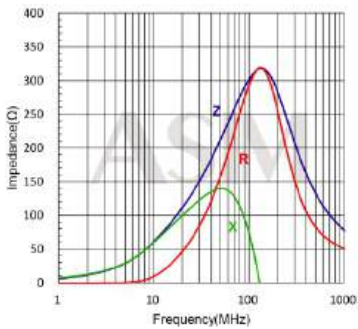
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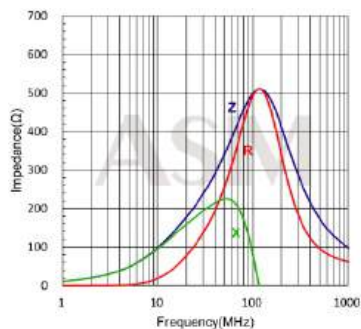
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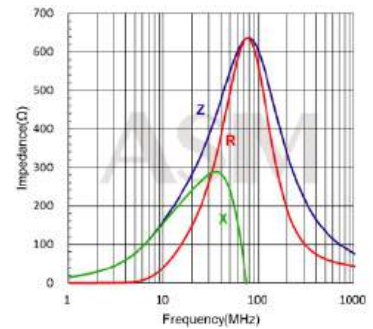
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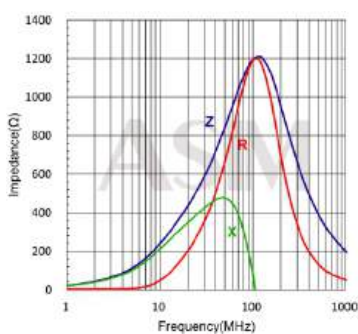
CVB3216E501T



CVB3216E601T



CVB3216E102T



### Measuring Equipment

Test Items	Device Model	Manufacturers
Impedance	4991A	Keysight Technologies
DC Resistance	4338A	Keysight Technologies



### RELIABILITY AND TEST CONDITIONS

Items	Requirements	Test Methods and Remarks																																
1. Operating Temperature Range		-55°C to +125°C																																
2. Storage Temperature Range		-55°C to +125°C																																
3. Terminal Strength	No removal or split of the termination or other defects shall occur.	<p>① Solder the chip to the testing jig (glass epoxy board shown as the following figure) using eutectic solder. Then apply a force in the direction of the arrow.</p> <p>② 2N force for 0603 series.</p> <p>③ 5N force for 1005 and 1608 series.</p> <p>④ 10N force for 2010, 2012, 3216, 4516 and 4030 series.</p> <p>⑤ Keep time: 10±1s</p>																																
4. Resistance to Flexure	No visible mechanical damage.	<p>① Solder the chip to the test jig (glass epoxy board) using a eutectic solder. Then apply a force in the direction shown as the following figure.</p> <p>② Flexure: 2mm</p> <p>③ Pressurizing Speed: 0.5mm/sec</p> <p>④ Keep time: ≥30 sec</p> <table border="1" style="margin-left: auto; margin-right: auto;"> <thead> <tr> <th>Type</th> <th>a</th> <th>b</th> <th>c</th> </tr> </thead> <tbody> <tr> <td>0603[0201]</td> <td>0.25</td> <td>0.8</td> <td>0.3</td> </tr> <tr> <td>1005[0402]</td> <td>0.4</td> <td>1.5</td> <td>0.5</td> </tr> <tr> <td>1608[0603]</td> <td>1.0</td> <td>3.0</td> <td>1.2</td> </tr> <tr> <td>2012[0805]</td> <td>1.2</td> <td>4.0</td> <td>1.65</td> </tr> <tr> <td>3216[1206]</td> <td>2.2</td> <td>5.0</td> <td>2.0</td> </tr> <tr> <td>4030[1612]</td> <td>1.9</td> <td>6.1</td> <td>3.2</td> </tr> <tr> <td>4516[1806]</td> <td>2.8</td> <td>8.5</td> <td>2.0</td> </tr> </tbody> </table>	Type	a	b	c	0603[0201]	0.25	0.8	0.3	1005[0402]	0.4	1.5	0.5	1608[0603]	1.0	3.0	1.2	2012[0805]	1.2	4.0	1.65	3216[1206]	2.2	5.0	2.0	4030[1612]	1.9	6.1	3.2	4516[1806]	2.8	8.5	2.0
Type	a	b	c																															
0603[0201]	0.25	0.8	0.3																															
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1608[0603]	1.0	3.0	1.2																															
2012[0805]	1.2	4.0	1.65																															
3216[1206]	2.2	5.0	2.0																															
4030[1612]	1.9	6.1	3.2																															
4516[1806]	2.8	8.5	2.0																															
5. Vibration	<p>① No visible mechanical damage.</p> <p>② Impedance change: Within ±20%.</p>	<p>① Solder the chip to the testing jig (glass epoxy board shown as the following figure) using eutectic solder.</p> <p>② The chip shall be subjected to a simple harmonic motion having total amplitude of 1.5 mm, the frequency being varied uniformly between the approximate limits of 10 and 55 Hz.</p> <p>③ The frequency range from 10 to 55 Hz and return to 10 Hz shall be traversed in approximately 1 minute. This motion shall be applied for a period of 2 hours in each 3 mutually perpendicular directions (total of 6 hours).</p>																																



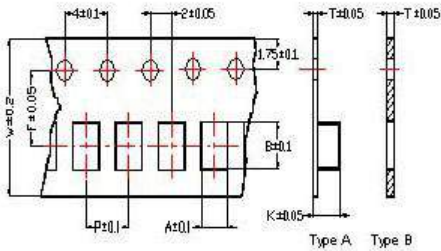


Items	Requirements	Test Methods and Remarks
6. Dropping	<ul style="list-style-type: none"> <li>① No visible mechanical damage.</li> <li>② Impedance change: Within <math>\pm 20\%</math>.</li> </ul>	<ul style="list-style-type: none"> <li>① Drop chip bead 10 times on a concrete floor from a height of 100 cm.</li> </ul>
7. Temperature	<ul style="list-style-type: none"> <li>① Impedance change should be within <math>\pm 20\%</math> of initial value measuring at <math>20^{\circ}\text{C}</math>.</li> </ul>	<ul style="list-style-type: none"> <li>① Temperature range: <math>-55^{\circ}\text{C}</math> to <math>+125^{\circ}\text{C}</math> Reference temperature: <math>+20^{\circ}\text{C}</math></li> </ul>
8. Solderability	<ul style="list-style-type: none"> <li>① No visible mechanical damage.</li> <li>② Wetting shall be exceeded 75% coverage for 0603 series, and 95% coverage for the other.</li> </ul>	<ul style="list-style-type: none"> <li>① Solder temperature: <math>240 \pm 2^{\circ}\text{C}</math></li> <li>② Duration: 3 sec</li> <li>③ Solder: Sn/3.0Ag/0.5Cu</li> <li>④ Flux: 25% Resin and 75% ethanol in weight</li> </ul>
9. Resistance to Soldering Heat	<ul style="list-style-type: none"> <li>① No visible mechanical damage.</li> <li>② Wetting shall be exceeded 75% coverage for 0603 series, and 95% coverage for the other</li> <li>③ Impedance change: Within <math>\pm 20\%</math>.</li> </ul>	<ul style="list-style-type: none"> <li>① Solder temperature: <math>260 \pm 3^{\circ}\text{C}</math></li> <li>② Duration: 5 sec</li> <li>③ Solder: Sn/3.0Ag/0.5Cu</li> <li>④ Flux: 25% Resin and 75% ethanol in weight</li> <li>⑤ The chip shall be stabilized at normal condition for 1~2 hours before measuring.</li> </ul>
10. Thermal Shock	<ul style="list-style-type: none"> <li>① No visible mechanical damage.</li> <li>② Impedance change: Within <math>\pm 20\%</math>.</li> </ul>	<ul style="list-style-type: none"> <li>① Temperature and time: <math>-55^{\circ}\text{C}</math> for <math>30 \pm 3</math> min <math>\rightarrow</math> <math>125^{\circ}\text{C}</math> for <math>30 \pm 3</math> min</li> <li>② Transforming interval: Max. 20 sec</li> <li>③ Tested cycle: 100 cycles</li> <li>④ The chip shall be stabilized at normal condition for 1~2 hours before measuring.</li> </ul> <p style="text-align: center;"> <math>125^{\circ}\text{C}</math>          Ambient          Temperature  <math>-55^{\circ}\text{C}</math>          30 min.          30 min.          20sec. (max.)     </p>
11. Resistance to Low Temperature	<ul style="list-style-type: none"> <li>① No visible mechanical damage.</li> <li>② Impedance change: Within <math>\pm 20\%</math>.</li> </ul>	<ul style="list-style-type: none"> <li>① Temperature: <math>-55 \pm 2^{\circ}\text{C}</math></li> <li>② Duration: <math>1000^{+24}</math> hours</li> <li>③ The chip shall be stabilized at normal condition for 1~2 hours before measuring.</li> </ul>
12. Damp Heat (Steady States)	<ul style="list-style-type: none"> <li>① No visible mechanical damage.</li> <li>② Impedance change: Within <math>\pm 20\%</math>.</li> </ul>	<ul style="list-style-type: none"> <li>① Temperature: <math>60 \pm 2^{\circ}\text{C}</math></li> <li>② Humidity: 90% to 95% RH</li> <li>③ Duration: <math>1000^{+24}</math> hours</li> <li>④ The chip shall be stabilized at normal condition for 1~2 hours before measuring.</li> </ul>
13. Loading Under Damp Heat	<ul style="list-style-type: none"> <li>① No visible mechanical damage.</li> <li>② Impedance change: Within <math>\pm 20\%</math>.</li> </ul>	<ul style="list-style-type: none"> <li>① Temperature: <math>60 \pm 2^{\circ}\text{C}</math></li> <li>② Humidity: 90% to 95% RH</li> <li>③ Duration: <math>1000^{+24}</math> hours</li> <li>④ Applied current: Rated current</li> <li>⑤ The chip shall be stabilized at normal condition for 1~2 hours before measuring.</li> </ul>
14. Loading at High Temperature (Life Test)	<ul style="list-style-type: none"> <li>① No visible mechanical damage.</li> <li>② Impedance change: Within <math>\pm 20\%</math>.</li> </ul>	<ul style="list-style-type: none"> <li>① Temperature: <math>125 \pm 2^{\circ}\text{C}</math></li> <li>② Duration: <math>1000^{+24}</math> hours</li> <li>③ Applied current: Rated current.</li> <li>④ The chip shall be stabilized at normal condition for 1~2 hours before measuring.</li> </ul>



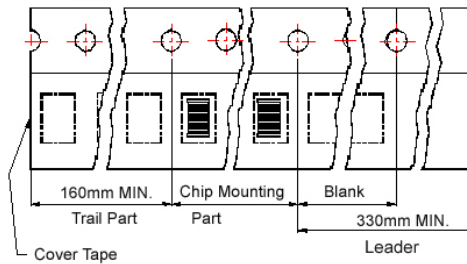
### Packaging Specifications

#### Tape Dimensions

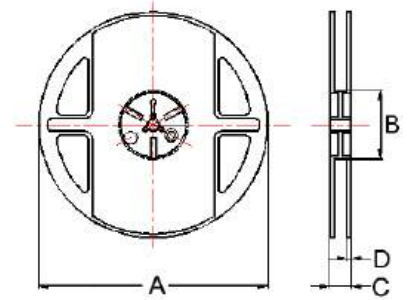


#### Tape Material

Carrier Tape: Polycarbonate (Tape A)  
 Carrier Tape: Paper (Tape B)  
 Cover Tape: Polystyrene



#### Reel Dimensions



### Dimensions in mm

TYPE	Tape Dimensions								Reel Dimensions				Quantity
	A	B	T	W	P	F	K	Tape	A	B	C	D	PCS / REEL
1005	0.65	1.15	0.60	8.0	2.0	3.5	-	B	178	60	12	2	10000
1608	1.05	1.85	0.95	8.0	4.0	3.5	-	B	178	60	12	2	4000
2012	1.50	2.30	0.97	8.0	4.0	3.5	-	B	178	60	12	2	4000
3216	1.88	3.50	0.22	8.0	4.0	3.5	1.27	A	178	60	12	2	3000